

Mhh Ishak

List of Publications by Year in descending order

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27
papers

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15
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28
all docs

28
docs citations

28
times ranked

107
citing authors

#	ARTICLE	IF	CITATIONS
1	Lattice Boltzmann method study of bga bump arrangements on void formation. Microelectronics Reliability, 2016, 56, 170-181.	1.7	29
2	Numerical Analysis of Nozzle Flow and Spray Characteristics from Different Nozzles Using Diesel and Biofuel Blends. Energies, 2019, 12, 281.	3.1	28
3	Effect of ILU dispensing types for different solder bump arrangements on CUF encapsulation process. Microelectronic Engineering, 2016, 163, 83-97.	2.4	26
4	Effect of thermocapillary action in the underfill encapsulation of multi-stack ball grid array. Microelectronics Reliability, 2016, 66, 143-160.	1.7	22
5	Lattice Boltzmann method study of effect three dimensional stacking-chip package layout on micro-void formation during encapsulation process. Microelectronics Reliability, 2016, 65, 205-216.	1.7	15
6	CUF scaling effect on contact angle and threshold pressure. Soldering and Surface Mount Technology, 2017, 29, 173-190.	1.5	15
7	Lattice Boltzmann Method of Different BGA Orientations on I-Type Dispensing Method. PLoS ONE, 2016, 11, e0159357.	2.5	14
8	Numerical study of the 3D Savonius turbine under stationary conditions. Engineering Failure Analysis, 2022, 136, 106199.	4.0	11
9	Effect of scale size, orientation type and dispensing method on void formation in the CUF encapsulation of BGA. Sadhana - Academy Proceedings in Engineering Sciences, 2018, 43, 1.	1.3	10
10	Lattice Boltzmann Model of 3D Multiphase Flow in Artery Bifurcation Aneurysm Problem. Computational and Mathematical Methods in Medicine, 2016, 2016, 1-17.	1.3	8
11	Numerical study on the influence of nozzle spray shape on spray characteristics using diesel and biofuel blends. Biofuels, 2021, 12, 1109-1121.	2.4	8
12	Comparative Study of Pressurized and Capillary Underfill Flow Using Lattice Boltzmann Method. Arabian Journal for Science and Engineering, 2019, 44, 7627-7652.	3.0	8
13	Optimization of 3D IC stacking chip on molded encapsulation process: a response surface methodology approach. International Journal of Advanced Manufacturing Technology, 2019, 103, 1139-1153.	3.0	7
14	Effect of hourglass shape solder joints on underfill encapsulation process: numerical and experimental studies. Soldering and Surface Mount Technology, 2020, 32, 147-156.	1.5	7
15	Three-dimensional CFD simulation of the stencil printing performance of solder paste. International Journal of Advanced Manufacturing Technology, 2020, 108, 3351-3359.	3.0	7
16	Study on the Fluid-Structure Interaction at Different Layout of Stacked Chip in Molded Packaging. Arabian Journal for Science and Engineering, 2017, 42, 4743-4757.	3.0	4
17	Effect of filling level and fillet profile on pin-through-hole solder joint. International Journal of Advanced Manufacturing Technology, 2019, 102, 1467-1485.	3.0	3
18	Effect of adhesive force on underfill process based on lattice Boltzmann method. Microelectronics International, 2020, 37, 54-63.	0.6	3

#	ARTICLE	IF	CITATIONS
19	Effect of relative humidity and wind on the human sneezing to prevent virus transmission: A numerical approach. <i>Aerosol Science and Technology</i> , 0, , 1-15.	3.1	3
20	Investigation of Aerodynamic Characteristics of a Wing Model With RGV Winglet. <i>Journal of Aerospace Technology and Management</i> , 2020, , .	0.3	3
21	Comparative Study of the Scaling Effect on Pressure Profiles in Capillary Underfill Process. <i>IOP Conference Series: Materials Science and Engineering</i> , 2017, 203, 012012.	0.6	2
22	Experiential study on temperature and emission performance of micro burner during porous media combustion. <i>IOP Conference Series: Materials Science and Engineering</i> , 2018, 370, 012057.	0.6	2
23	Scaling Effect on Velocity Profiles in Capillary Underfill Flow. <i>IOP Conference Series: Materials Science and Engineering</i> , 2017, 203, 012013.	0.6	1
24	Lattice-Boltzmann analysis of pressurized underfill process for I-type dispensing method. <i>AIP Conference Proceedings</i> , 2016, , .	0.4	0
25	FVM based simulation on multi-stack ball grid array (BGA). <i>AIP Conference Proceedings</i> , 2016, , .	0.4	0
26	Numerical simulation of thermal fluid-structure interaction on flexible PCB in reflow soldering atmosphere. <i>AIP Conference Proceedings</i> , 2019, , .	0.4	0
27	Lead-free solder SAC 305 Volume Reduction and Cold Slump after Stencil Printing Process. <i>IOP Conference Series: Materials Science and Engineering</i> , 2020, 852, 012084.	0.6	0